

Hybrid Circuit Technology for Wireless Applications

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Abstract

A design methodology for wireless circuits using thick film technology will be discussed. Aurel's almost 50 years of experience using thick film for microelectronics including wireless applications will be discussed. The attributes of thick film will be compared to thin film technology, PCB FR4 architectures, and other substrate materials such as Alumina and Aluminum nitride. A video will demonstrate the fine line technology with a New Generation of Fully Automatic Screen Printing Lines for standard thick film hybrids and fine line thick film solutions to achieve fine lines up to 20 microns and fine gaps up to 30 microns.